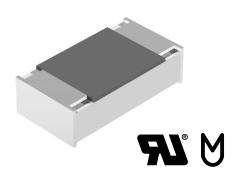
HALOGEN FREE





## **Thin Film Chip Fuses**



MFU Thin Film Chip Fuses are the perfect choice for the most fields of modern electronics. The highly controlled manufacturing thin film process guarantees an outstanding stability of fusing characteristics. Typical applications include information technology, telecommunication, medical equipment, industrial, audio/video, and automotive electronics.

#### **FEATURES**

- · Advanced thin film technology
- · Very quick acting fuse characteristics
- · Outstanding stability of fusing characteristics
- Standard SMD sizes
- Green product, supports lead (Pb)-free soldering
- Halogen-free according to IEC 61249-2-21 definition
- Compliant to RoHS directive 2002/95/EC

#### **APPLICATIONS**

- Information technology
- · Industrial electronics
- Automotive electronics
- Telecommunication
- Medical equipment
- · Audio/video electronics

SIZE										
INCH	0402	0603	0805	1206						
METRIC	1005M	1608M	2012M	3216M						

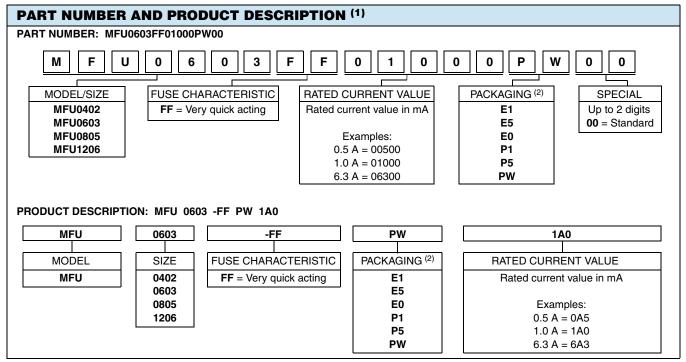
TECHN	ICAL SPECIFICA	TIONS				
DESCRIPT	ION	MFU 0402	MFU 0603	MFU 0805	MFU 1206	
Metric size		1005M	1608M	2012M	3216M	
Rated Curre	ent range I <sub>R</sub>	0.5 A to 3.15 A	0.5 A to 5.0 A	0.5 A to 5.0 A	0.5 A to 6.3 A	
Rated volta	ge, <i>U</i> <sub>max.</sub> DC	32 V	32 V	32 V	63 V	
Breaking Capacity, I <sub>max.</sub> at U <sub>max.</sub> DC		50 A at 32 V	50 A at 32 V	50 A at 32 V	50 A at 63 V	
Voltage drop at 1 x I <sub>R</sub>		90 mV to 368 mV	85 mV to 361 mV	98 mV to 374 mV	116 mV to 433 mV	
Cold resista	ance at 0.1 x I <sub>R</sub>	22 m $\Omega$ to 560 m $\Omega$	13 m $\Omega$ to 550 m $\Omega$	15 m $\Omega$ to 570 m $\Omega$	14 m $\Omega$ to 660 m $\Omega$	
Climatic cat	tegory (LCT/UCT/days)	55/125/56	55/125/56	55/125/56	55/125/56	
	continuous ang at $\vartheta_{\rm amb}$ = 23 °C	0.7 x I <sub>R</sub>	0.7 x I <sub>R</sub>	0.7 x I <sub>R</sub>	0.7 x I <sub>R</sub>	
	UL recognition file	E253806	E253806	E253806	E253806	
Approval	IEC 60127-4	n/a	Refer to table: MFU 0603 RATING		Refer to table: MFU 1206 RATING	
FITobserved		≤ 0.2 x 10 <sup>-9</sup> /h	≤ 0.2 x 10 <sup>-9</sup> /h	≤ 0.2 x 10 <sup>-9</sup> /h	≤ 0.2 x 10 <sup>- 9</sup> /h	

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## Vishay Beyschlag

### Thin Film Chip Fuses





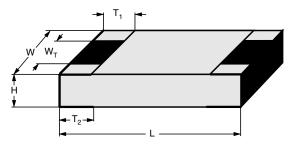
#### Notes

- (1) Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION
- (2) Please refer to table PACKAGING

PACKAGING									
MODEL	REEL								
WODEL	DIAMETER	PIECES/REEL	CODE						
	180 mm/7"	1000	E1						
MFU0402	180 mm/7"	5000	E5						
	180 mm/7"	10 000	E0						
	180 mm/7"	1000	P1						
MFU0603	180 mm/7"	5000	P5						
	330 mm/13"	20 000	PW						
	180 mm/7"	1000	P1						
MFU0805	180 mm/7"	5000	P5						
	330 mm/13"	20 000	PW						
	180 mm/7"	1000	P1						
MFU1206	180 mm/7"	5000	P5						
	330 mm/13"	20 000	PW						

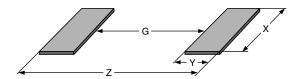


#### **DIMENSIONS**



DIMENS	<b>DIMENSIONS</b> - Chip fuse types, mass and relevant physical dimensions										
TYPE	H (mm)	L (mm)	W (mm)	W <sub>T</sub> (mm)	T <sub>1</sub> (mm)	T <sub>2</sub> (mm)	MASS (mg)				
MFU 0402	0.32 ± 0.07	1.0 ± 0.05	$0.5 \pm 0.05$	> 75 % of W	0.2 + 0.1/- 0.15	0.2 ± 0.1	0.65				
MFU 0603	0.45 + 0.1/- 0.05	1.55 ± 0.05	0.85 ± 0.1	> 75 % of W	0.3 + 0.15/- 0.2	0.3 + 0.15/- 0.2	1.9				
MFU 0805	0.45 + 0.1/- 0.05	2.0 ± 0.1	1.25 ± 0.15	> 75 % of W	0.4 + 0.1/- 0.2	0.4 + 0.1/- 0.2	4.7				
MFU 1206	0.55 ± 0.1	3.2 + 0.1/- 0.2	1.6 ± 0.15	> 75 % of W	0.5 ± 0.25	0.5 ± 0.25	9.5				

### **SOLDER PAD DIMENSIONS**



RECOMME	RECOMMENDED SOLDER PAD DIMENSIONS											
		WAVE SO	LDERING			REFLOW SOLDERING						
TYPE	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)				
MFU 0402	-	-	-	-	0.35	0.55	0.55	1.45				
MFU 0603	0.55	1.10	1.10	2.75	0.65	0.70	0.95	2.05				
MFU 0805	0.80	1.25	1.50	3.30	0.90	0.90	1.40	2.70				
MFU 1206	1.40	1.50	1.90	4.40	1.50	1.15	1.75	3.80				

#### Note

• The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters.

Document Number: 28747 Revision: 06-May-10

## Vishay Beyschlag

## Thin Film Chip Fuses



MFU	J 040	2 RATING	i - Very qu	ick acting (FF	)					
SIZE	FUSE CHAR.	RATED CURRENT (1)	RATED VOLTAGE	PRE-ARCING (2) I <sup>2</sup> t at 10 x I <sub>R</sub>	VOLT. DROP <sup>(2)</sup> at 1 x I <sub>R</sub>	COLD RESIS (2) at 0.1 x I <sub>R</sub>	BREAKING CAPACITY DC	MARK.	APPROVAL	PART NUMBER (3)(4)
		500 mA <sup>(5)</sup>	32 V	0.0009 A <sup>2</sup> s	368 mV	560 mΩ	50 A at 32 V	-	UL	MFU0402FF00500E500
		630 mA <sup>(5)</sup>	32 V	0.0014 A <sup>2</sup> s	331 mV	400 m $\Omega$	50 A at 32 V	-	UL	MFU0402FF00630E500
		750 mA <sup>(5)</sup>	32 V	0.0020 A <sup>2</sup> s	275 mV	280 mΩ	50 A at 32 V	-	UL	MFU0402FF00750E500
		800 mA	32 V	0.0023 A <sup>2</sup> s	231 mV	220 m $\Omega$	50 A at 32 V	-	UL	MFU0402FF00800E500
		1.0 A	32 V	0.0028 A <sup>2</sup> s	184 mV	140 m $\Omega$	50 A at 32 V	-	UL	MFU0402FF01000E500
		1.25 A	32 V	0.0039 A <sup>2</sup> s	159 mV	97 mΩ	50 A at 32 V	-	UL	MFU0402FF01250E500
0402	FF	1.5 A	32 V	0.0059 A <sup>2</sup> s	146 mV	74 mΩ	50 A at 32 V	-	UL	MFU0402FF01500E500
		1.6 A	32 V	0.0065 A <sup>2</sup> s	136 mV	65 mΩ	50 A at 32 V	-	UL	MFU0402FF01600E500
		1.75 A	32 V	0.0077 A <sup>2</sup> s	124 mV	54 mΩ	50 A at 32 V	-	UL	MFU0402FF01750E500
		2.0 A	32 V	0.0101 A <sup>2</sup> s	115 mV	44 mΩ	50 A at 32 V	-	UL	MFU0402FF02000E500
		2.5 A	32 V	0.0157 A <sup>2</sup> s	107 mV	33 mΩ	50 A at 32 V	-	UL	MFU0402FF02500E500
		3.0 A	32 V	0.0227 A <sup>2</sup> s	95 mV	24 mΩ	50 A at 32 V	-	UL	MFU0402FF03000E500
		3.15 A	32 V	0.0250 A <sup>2</sup> s	90 mV	22 mΩ	50 A at 32 V	-	UL	MFU0402FF03150E500

#### Notes

- (1) Other values of rated current are available on request
- (2) Typical values
- (3) For packages with 1000 pieces, please use for packaging E1 instead of E5 (4) For packages with 10 000 pieces, please use for packaging E0 instead of E5
- (5) Available on request

MFU	J 060	3 RATING	i - Very qu	ick acting (FF	)					
SIZE	FUSE CHAR.	RATED CURRENT (6)	RATED VOLTAGE	PRE-ARCING <sup>(7)</sup> I <sup>2</sup> t at 10 x I <sub>R</sub>	VOLT. DROP <sup>(7)</sup> at 1 x I <sub>R</sub>	COLD RESIS (7) at 0.1 x I <sub>R</sub>	BREAKING CAPACITY DC	MARK.	APPROVAL	PART NUMBER (8)(9)
		500 mA	32 V	0.0009 A <sup>2</sup> s	361 mV	550 m $\Omega$	50 A at 32 V	F	UL/IEC	MFU0603FF00500P500
		630 mA	32 V	0.0014 A <sup>2</sup> s	331 mV	400 m $\Omega$	50 A at 32 V	CT	UL	MFU0603FF00630P500
		750 mA	32 V	0.0020 A <sup>2</sup> s	258 mV	262 m $\Omega$	50 A at 32 V	G	UL	MFU0603FF00750P500
		800 mA	32 V	0.0023 A <sup>2</sup> s	249 mV	237 m $\Omega$	50 A at 32 V	CV	UL	MFU0603FF00800P500
		1.0 A	32 V	0.0028 A <sup>2</sup> s	223 mV	170 m $\Omega$	50 A at 32 V	Н	UL/IEC	MFU0603FF01000P500
		1.25 A	32 V	0.0039 A <sup>2</sup> s	180 mV	110 m $\Omega$	50 A at 32 V	J	UL	MFU0603FF01250P500
		1.5 A	32 V	0.0059 A <sup>2</sup> s	155 mV	79 m $Ω$	50 A at 32 V	K	UL	MFU0603FF01500P500
0603	FF	1.6 A	32 V	0.0065 A <sup>2</sup> s	159 mV	76 m $Ω$	50 A at 32 V	EF	UL/IEC	MFU0603FF01600P500
0003	FF	1.75 A	32 V	0.0077 A <sup>2</sup> s	138 mV	60 mΩ	50 A at 32 V	L	UL	MFU0603FF01750P500
		2.0 A	32 V	0.0101 A <sup>2</sup> s	150 mV	57 mΩ	50 A at 32 V	N	UL/IEC	MFU0603FF02000P500
		2.5 A	32 V	0.0157 A <sup>2</sup> s	121 mV	37 mΩ	50 A at 32 V	0	UL	MFU0603FF02500P500
		3.0 A	32 V	0.0227 A <sup>2</sup> s	126 mV	32 mΩ	50 A at 32 V	Р	UL	MFU0603FF03000P500
		3.15 A	32 V	0.0250 A <sup>2</sup> s	120 mV	29 mΩ	50 A at 32 V	EL	UL/IEC	MFU0603FF03150P500
		3.5 A	32 V	0.0308 A <sup>2</sup> s	106 mV	23 mΩ	50 A at 32 V	R	UL	MFU0603FF03500P500
		4.0 A	32 V	0.0403 A <sup>2</sup> s	100 mV	19 mΩ	50 A at 32 V	S	UL	MFU0603FF04000P500
		5.0 A	32 V	0.2275 A <sup>2</sup> s	85 mV	13 m $\Omega$	50 A at 32 V	Т	UL	MFU0603FF05000P500

#### Notes

- (6) Other values of rated current are available on request
- (7) Typical values
- (8) For packages with 1000 pieces, please use for packaging P1 instead of P5
- (9) For packages with 20 000 pieces, please use for packaging PW instead of P5





MFU	J 080	5 RATING	i - Very qu	ick acting (FF	)					
SIZE	FUSE CHAR.	RATED CURRENT (1)	RATED VOLTAGE	PRE-ARCING (2) I <sup>2</sup> t at 10 x I <sub>R</sub>	VOLT. DROP <sup>(2)</sup> at 1 x I <sub>R</sub>	COLD RESIS (2) at 0.1 x I <sub>R</sub>	BREAKING CAPACITY DC	MARK.	APPROVAL	PART NUMBER (3)(4)
		500 mA	32 V	0.0009 A <sup>2</sup> s	374 mV	570 mΩ	50 A at 32 V	F	UL	MFU0805FF00500P500
		630 mA	32 V	0.0014 A <sup>2</sup> s	347 mV	420 m $\Omega$	50 A at 32 V	CT	UL	MFU0805FF00630P500
		750 mA	32 V	0.0021 A <sup>2</sup> s	280 mV	285 m $\Omega$	50 A at 32 V	G	UL	MFU0805FF00750P500
		800 mA	32 V	0.0023 A <sup>2</sup> s	262 mV	250 mΩ	50 A at 32 V	CV	UL	MFU0805FF00800P500
		1.0 A	32 V	0.0028 A <sup>2</sup> s	243 mV	185 m $\Omega$	50 A at 32 V	Н	UL	MFU0805FF01000P500
		1.25 A	32 V	0.0040 A <sup>2</sup> s	205 mV	125 m $\Omega$	50 A at 32 V	J	UL	MFU0805FF01250P500
		1.5 A	32 V	0.0059 A <sup>2</sup> s	171 mV	87 mΩ	50 A at 32 V	K	UL	MFU0805FF01500P500
0805	FF	1.6 A	32 V	0.0065 A <sup>2</sup> s	164 mV	78 mΩ	50 A at 32 V	EF	UL	MFU0805FF01600P500
0003		1.75 A	32 V	0.0077 A <sup>2</sup> s	161 mV	70 mΩ	50 A at 32 V	L	UL	MFU0805FF01750P500
		2.0 A	32 V	0.0101 A <sup>2</sup> s	176 mV	67 mΩ	50 A at 32 V	N	UL	MFU0805FF02000P500
		2.5 A	32 V	0.0157 A <sup>2</sup> s	131 mV	40 mΩ	50 A at 32 V	0	UL	MFU0805FF02500P500
		3.0 A	32 V	0.0227 A <sup>2</sup> s	134 mV	34 mΩ	50 A at 32 V	Р	UL	MFU0805FF03000P500
		3.15 A	32 V	0.0250 A <sup>2</sup> s	128 mV	31 mΩ	50 A at 32 V	EL	UL	MFU0805FF03150P500
		3.5 A	32 V	0.0308 A <sup>2</sup> s	119 mV	26 mΩ	50 A at 32 V	R	UL	MFU0805FF03500P500
		4.0 A	32 V	0.0403 A <sup>2</sup> s	105 mV	20 mΩ	50 A at 32 V	S	UL	MFU0805FF04000P500
		5.0 A	32 V	0.2275 A <sup>2</sup> s	98 mV	15 mΩ	50 A at 32 V	Т	UL	MFU0805FF05000P500

MFU	J 120	6 RATING	- Very qu	ick acting (FF	)					
SIZE	FUSE CHAR.	RATED CURRENT (1)	RATED VOLTAGE	PRE-ARCING (2) I <sup>2</sup> t at 10 x I <sub>R</sub>	VOLT. DROP (2) at 1 x I <sub>R</sub>	COLD RESIS (2) at 0.1 x I <sub>R</sub>	BREAKING CAPACITY DC	MARK.	APPROVAL	PART NUMBER <sup>(3)(4)</sup>
		500 mA	63 V	0.0009 A <sup>2</sup> s	433 mV	660 m $\Omega$	50 A at 63 V	F	UL/IEC	MFU1206FF00500P500
		630 mA	63 V	0.0014 A <sup>2</sup> s	372 mV	450 m $\Omega$	50 A at 63 V	CT	UL	MFU1206FF00630P500
		750 mA	63 V	0.0022 A <sup>2</sup> s	325 mV	330 m $\Omega$	50 A at 63 V	G	UL	MFU1206FF00750P500
		800 mA	63 V	0.0023 A <sup>2</sup> s	273 mV	260 m $\Omega$	50 A at 63 V	CV	UL	MFU1206FF00800P500
		1.0 A	63 V	0.0028 A <sup>2</sup> s	262 mV	200 m $\Omega$	50 A at 63 V	Н	UL/IEC	MFU1206FF01000P500
		1.25 A	63 V	0.0041 A <sup>2</sup> s	230 mV	140 m $\Omega$	50 A at 63 V	J	UL	MFU1206FF01250P500
		1.5 A	63 V	0.0059 A <sup>2</sup> s	207 mV	105 m $\Omega$	50 A at 63 V	K	UL	MFU1206FF01500P500
		1.6 A	63 V	0.0066 A <sup>2</sup> s	168 mV	$80~\text{m}\Omega$	50 A at 63 V	EF	UL/IEC	MFU1206FF01600P500
1206	FF	1.75 A	63 V	0.0077 A <sup>2</sup> s	174 mV	$76~\text{m}\Omega$	50 A at 63 V	L	UL	MFU1206FF01750P500
		2.0 A	63 V	0.0102 A <sup>2</sup> s	181 mV	$69~\text{m}\Omega$	50 A at 63 V	N	UL/IEC	MFU1206FF02000P500
		2.5 A	63 V	0.0159 A <sup>2</sup> s	161 mV	49 m $\Omega$	50 A at 63 V	0	UL	MFU1206FF02500P500
		3.0 A	63 V	0.0229 A <sup>2</sup> s	173 mV	44 m $\Omega$	50 A at 63 V	Р	UL	MFU1206FF03000P500
		3.15 A	63 V	0.0251 A <sup>2</sup> s	153 mV	$37~\text{m}\Omega$	50 A at 63 V	EL	UL/IEC	MFU1206FF03150P500
		3.5 A	63 V	0.0310 A <sup>2</sup> s	161 mV	35 m $\Omega$	50 A at 63 V	R	UL	MFU1206FF03500P500
		4.0 A	63 V	0.0404 A <sup>2</sup> s	147 mV	28 m $\Omega$	50 A at 63 V	S	UL	MFU1206FF04000P500
		5.0 A	63 V	0.2275 A <sup>2</sup> s	131 mV	20 m $Ω$	50 A at 63 V	Т	UL	MFU1206FF05000P500
		6.3 A	63 V	0.5160 A <sup>2</sup> s	116 mV	14 m $\Omega$	50 A at 63 V	ET	UL	MFU1206FF06300P500

#### Notes

- Other values of rated current are available on request
- (2) Typical values
- (3) For packages with 1000 pieces, please use for packaging P1 instead of P5
  (4) For packages with 20 000 pieces, please use for packaging PW instead of P5

## Vishay Beyschlag

### Thin Film Chip Fuses



#### **DESCRIPTION**

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body. The fuse elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual fuses. Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3**.

#### **APPROVALS**

The fuses are tested in accordance with IEC 60127-4 and UL 248-14 which refers to UL 248-1, IEC 60127-1 and IEC 60068 series. Approval of conformity is indicated by the UMF logo on the package label. Recognition by Underwriter Laboratories Inc. is indicated by the UL logo on the package label.





Lead (Pb)-free Identification on the Package Label

#### **ASSEMBLY**

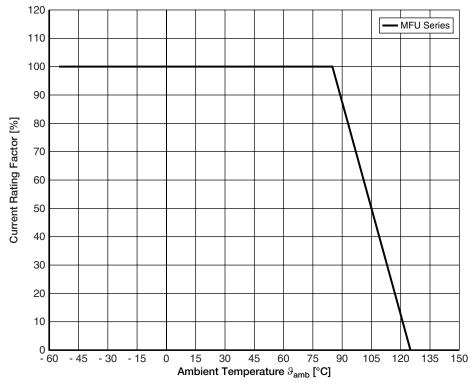
The fuses are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The fuses are RoHS compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing. Solderability is specified for 2 years after production or re-qualification. The permitted storage time is 20 years.

All products comply with the CEFIC-EECA-EICTA list of legal restrictions on hazardous substances.

This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2002/95/EC Restriction of the use of Hazardous Substances Directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

#### **FUNCTIONAL PERFORMANCE**



Current Rating Factor (1) vs. Ambient Temperature  $\vartheta_{amb}$ 

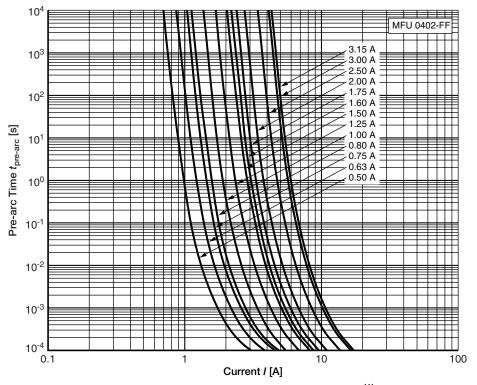
#### Note

(1) Current rating factor is in addition to the given permissible continuous current rating of 0.7

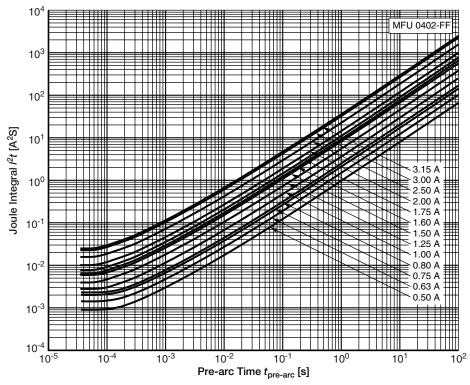




#### **FUNCTIONAL PERFORMANCE**



Typical  $t_{\rm pre-arc}$  vs. I characteristic of MFU 0402  $^{(1)}$ 

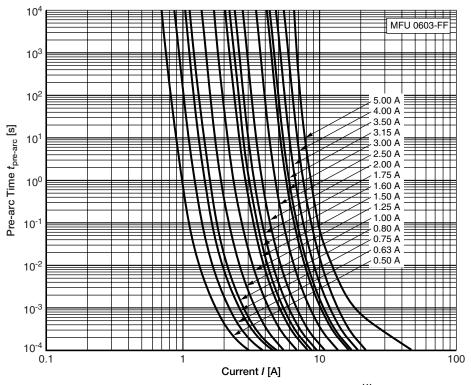


Typical  $f^2t$  vs.  $t_{\text{pre-arc}}$  characteristic of MFU 0402 (1)

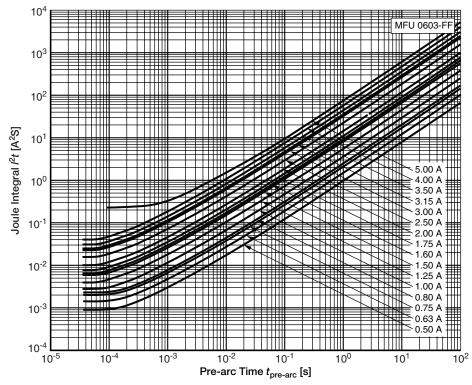
Note



#### **FUNCTIONAL PERFORMANCE**



Typical  $t_{\rm pre-arc}$  vs. I characteristic of MFU 0603  $^{(1)}$ 

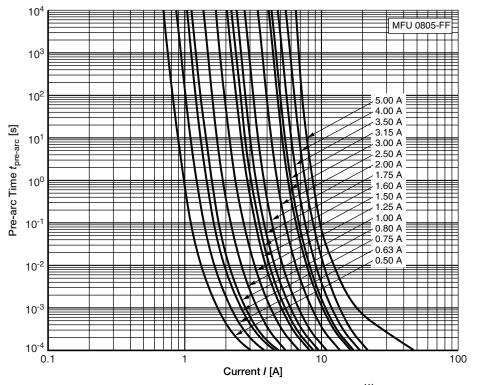


Typical Pt vs.  $t_{pre-arc}$  characteristic of MFU 0603 (1)

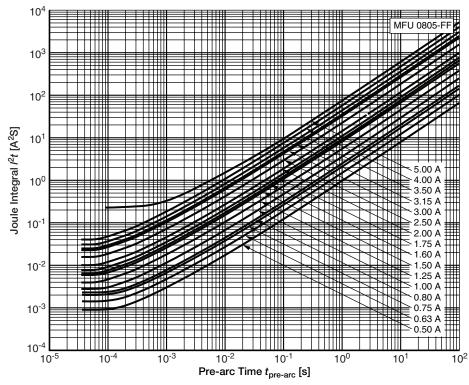
Note



#### **FUNCTIONAL PERFORMANCE**



Typical  $t_{\rm pre-arc}$  vs. I characteristic of MFU 0805  $^{(1)}$ 

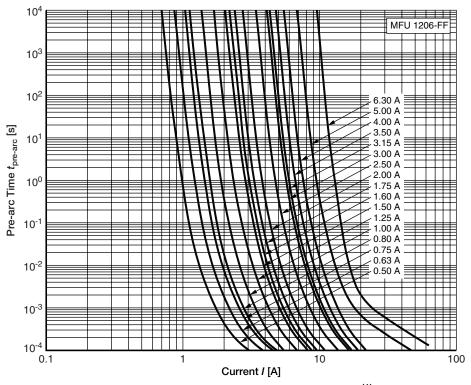


Typical  $l^2t$  vs.  $t_{\text{pre-arc}}$  characteristic of MFU 0805 (1)

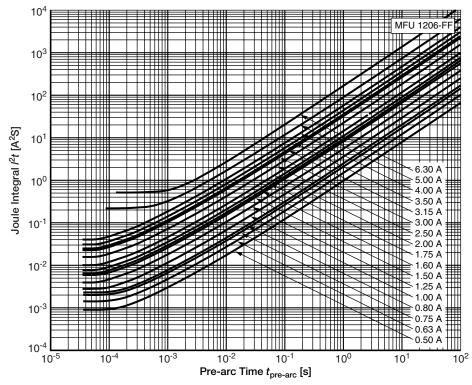
Note



#### **FUNCTIONAL PERFORMANCE**



Typical  $t_{\rm pre-arc}$  vs. I characteristic of MFU 1206  $^{(1)}$ 



Typical I<sup>2</sup>t vs. t<sub>pre-arc</sub> characteristic of MFU 1206 (1)

Note





## Vishay Beyschlag

#### **TEST AND REQUIREMENTS**

All tests are carried out in accordance with the following specifications:

IEC 60127-1, Miniature fuse - Part 1: Definitions for miniature fuses and general requirements for miniature fuse-links

IEC 60127-4, Universal Modular Fuse Links (UMF)

UL 248-1, Low voltage fuses - Part 1: General requirements

UL 248-14, Low voltage fuses - Part 14: Supplemental fuses

For the full test schedule refer to the documents listed above. The testing also covers most of the requirements specified by METI and CCC.

The tests are carried out in accordance with IEC 60068 and under standard atmospheric conditions in accordance with IEC 60068-1, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower category temperature, upper category temperature; damp heat, long term, 56 days) is valid.

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

The components are mounted for testing on printed-circuit boards in accordance with IEC 60127-4, unless otherwise specified.

The requirements stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of IEC 60127-1 and IEC 60127-4 respectively. However, some additional tests and a number of improvements against those minimum requirements have been included.

TEST F	PROCED	URES AND R	EQUIREMENTS				
IEC 60127-4 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PRO	CEDURE		REQUIREMENTS PERMISSIBLE CHANGE	
8.3.2	21 (U <sub>e1</sub> )	Substrate bending	Dep rate 1		No visible damage $\Delta R/R \le \pm 10 \%$		
8.6.2	58 (Td)	Solderability	Solder bath non-ac (215 ± 3)	Good tinning (≥ 95 % covered); no visible damage			
0.0.2	36 (14)	Solderability	Solder bath method; non-ac (245 ± 3)	Good tinning (≥ 95 % covered); no visible damage			
		Resistance to	Solder (260 ± 5)	No visible damage $\Delta R/R \le \pm 10 \%$			
8.7.2	58 (Td)	soldering heat	(IR/forced	w method 2 gas convection °C; (10 ± 1)		No visible damage $\Delta R/R \le \pm 10 \%$	
		Time/current	Cold resistance at 0.1 x I <sub>R</sub> ;	MFU 0402	I <sub>R</sub> ≤ 0.75 A	At 1.25 x $I_R$ , $t_{pre-arc} > 1$ h at 2.0 x $I_R$ , $t_{pre-arc} < 60$ s at 10 x $I_R$ , $t_{pre-arc} < 0.001$ s	
9.2.1	_	characteristics	destructive testing under	MFU 0402	$0.8 \text{ A} \le I_{\text{R}} \le 3.15 \text{ A}$		
		at nominal temperature	overcurrent conditions (DC-Current)	MFU 0603	<i>I</i> <sub>R</sub> ≤ 5.0 A	At 1.25 x $I_R$ , $t_{pre-arc} > 1 h$	
		р станала	(= 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	MFU 0805	<i>I</i> <sub>R</sub> ≤ 5.0 A	at 2.0 x $I_R$ , $t_{pre-arc} < 5$ s at 10 x $I_R$ , $t_{pre-arc} < 0.001$ s	
				MFU 1206	<i>I</i> <sub>R</sub> ≤ 6.3 A	,	
9.3.2	-	Breaking capacity	50 A at acc. to	Optical inspection with naked eye no visible damage			
9.3.3	-	Residual resistance	50 A at acc. to	Insulation resistance at 2.0 x $U_{\rm R}$ (DC) higher than 0.1 M $\Omega$			

## **MFU Series**

# Vishay Beyschlag

## Thin Film Chip Fuses



TEST F	PROCED	URES AND RE	QUIREMENTS			
IEC 60127-4 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PRO	CEDURE		REQUIREMENTS PERMISSIBLE CHANGE
			a) I = 1.0 x I <sub>R</sub> (DC)	MFU 0402	<i>I</i> <sub>R</sub> ≤ 3.15 A	
		Endurance test	1.0 h on; 0.25 h off; 23 °C; 100 times	MFU 0603	<i>I</i> <sub>R</sub> ≤ 3.15 A	No visible damage
9.4	-	acc. to IEC 60127-1	b) <i>I</i> = 1.25 x <i>I</i> <sub>R</sub> (DC) 1.0 h on	MFU 0805	<i>I</i> <sub>R</sub> ≤ 3.15 A	Δ <i>R</i> / <i>R</i> ≤ ± 10 %
			23 °C; 1 time	MFU 1206	<i>I</i> <sub>R</sub> ≤ 3.15 A	
9.5	-	Maximum sustained dissipation acc. to IEC 60127-1	Calculation in accordance	ce with results	s of clause 9.4 b)	Dissipation ≤ acc. to IEC 60127-4 table 2
				MFU 0402	<i>I</i> <sub>R</sub> ≤ 3.15 A	
		Fuse-link	The test is performed	MFU 0603	<i>I</i> <sub>R</sub> ≤ 3.15 A	Temperature rise of terminals
9.7	-	temperature	during the final 5 min of clause 9.4 b)	MFU 0805	<i>I</i> <sub>R</sub> ≤ 3.15 A	≤ 85 K
				MFU 1206	<i>I</i> <sub>R</sub> ≤ 3.15 A	]
		Verification of		MFU 0402	<i>I</i> <sub>R</sub> ≤ 3.15 A	Temperature rise
		temprise and current- carrying	/-10×/ (DC)	MFU 0603	<i>I</i> <sub>R</sub> ≤ 5.0 A	of hot spot ≤ 75 K
-	-	capacity acc. to UL 248-14	$I = 1.0 \times I_{R} (DC)$	MFU 0805	<i>I</i> <sub>R</sub> ≤ 5.0 A	acc. to
		clause 8.2.3		MFU 1206	<i>I</i> <sub>R</sub> ≤ 6.3 A	UL 248-14 clause 8.2.4
-	78 (Cab)	Damp heat, steady state		°C; 56 days; ± 3) % RH		$\Delta R/R \le \pm 10 \%$ I-t characteristic
-	14 (Na)	Rapid change of temperature	30 m 30 m LCT UCT	nin at LCT; nin at UCT; = - 55 °C; = 125 °C; cycles		Δ <i>R/R</i> ≤ ± 10 %
-	6 (Fc)	Vibration	Enduranc 10 Hz no re amplitud ≤ 200	Δ <i>R/R</i> ≤ ± 10 %		
-	45 (XA)	Component solvent resistance	Isopro 50 °C	No visible damage		
-	45 (XA)	Solvent resistance of marking	lsopro 50 °C; meth	Marking legible, no visible damage		
-	21 (Ue <sub>3</sub> )	Shear (adhesion)	RR 1 RR 2012M ar	45 N	No visible damage	
-	-	Flammability	IEC 6	60695-2-2, ame test; 10		No burning after 30 s

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